查询BU05MC供应商

コモンモードチョークコイル (DC、信号ライン用) SMDタイプ

COMMON MODE CHOKE COILS (FOR DC AND SIGNAL LINES)

SMD TYPE

OPERATING TEMP. -25~+105℃(製品自己発熱を含む) (Including self-generated heat) 等価回路 CM04RC CM04RC (4 Lines) Type (2 Lines) Type (3 Lines) Type (2 Lines) Type (3 Lines) Type 7 Equivalent circuits 9-700-6 3 6 (5) 6 5 6 4 6 5 4 Jan 1 739-O 0 0 3 4 9 2



捷多邦,专业PCB打样工厂,24小时加急出货

WWW.DZSG.CO

特長 **FEATURES**

CM04RC•BU05MC

- ·SMT対応
- ・高結合なコイル構造によりコモンモードノイズの除去に最適

CM04CR / BU05MC

- · Available in embossed tape and reel.
- Highly coupled coil construction ideal for common mode noise attenu-

用途 APPLICATIONS

- ・多機<mark>能電話機,PBX、FAXなど外線の不要</mark>幅射電界および放送波に対するイ ミュニティ対策
- ・各種電子機器のDCラインのノイズ対策
- ・ACアダプタ、バッテリーチャージャー及び各種デジタル機器の電源2次側 ライン、信号ラインの不要幅射対策
- ・DVC,DSC等の電源、2次側DCラインの不要輻射対策。
- ・パーソナルコンピューター、プリンター、スキャナー等のUSB(D+,D-)及 びIEEE1394の高速差動伝送のノイズ除去。
- · Immunity against undesirable external line radiation fields and broadcast waves generated by multifunction telephone sets, PBXs, and facsimile ma-
- · Preventive measure against DC line noise in electronic equipment.
- Suppresses radiated emissions from secondary power supplies and signal lines on AC adapters, battery chargers, and digital equipment.
- Excellent for reducing radiated noise in DVC (digital video cameras) and DSC (digital still cameras)
- Offers high speed differential mode noise attenuation in USB and IEEE1394 connectors in personal computers, printers, scanners and other computer peripherals

形名表記法 ORDERING CODE

形式 CM コモンモードチョークコイル BU

形状 RC 面実装タイプ MC

試作番号 $01 \sim 13$

包装記号

| コアの長辺寸法(mm) | | | | | |
|-------------|-----|--|--|--|--|
| 04 | 3.5 | | | | |
| 05 | 5.0 | | | | |
| | | | | | |

当社管理番号 標準品

Surface mount type

Type CM

Common mode choke coils

Shape RC MC

3

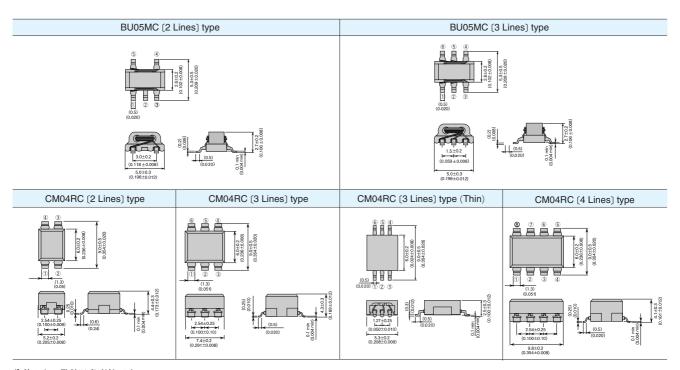
Product classification code 01 to 13

5 Packaging Taped products





外形寸法 EXTERNAL DIMENSIONS



公差のない数値は参考値です。 The values without tolerance are for reference only.

アイテム一覧 PART NUMBERS

CM04RCタイプ

| CIVIO4HC X 1 7 | | | | | | |
|---------------------|----------------------|------------------------------------------|----------------------------------------|----------------------------------------|----------------------------------------|-------------------------------------------------|
| 形名 Ordering code | ライン数 No. of Lines | インピーダンス Impedance [Ω] (typical) | 直流抵抗 DC resistance [Ω] (max.) | 定格電流 Rated current [A] (max.) | 定格電圧 Rated voltage [V] (D.C.) | 絶縁抵抗 Insulation resistance [MΩ] (min.) |
| CM04RC01T | | 800 (at 100MHz) | 0.06 | 1.5 | | |
| CM04RC03T | | 500 (at 480MHz) | 0.06 | 2.0 | | |
| CM04RC04T | 2 | 900 (at 15MHz) | 0.1 | 1.0 | | |
| CM04RC07T | _ | 500 (at 160MHz) | 0.06 | 2.5 | 50 | 100 |
| CM04RC09T | | 270 (at 200MHz) | 0.03 | 3.0 | 50 | 100 |
| CM04RC10T | | 100 (at 200MHz) | 0.02 | 4.0 | | |
| CM04RC02T | 3 | 1000 (at 100MHz) | 0.18 | 0.5 | | |
| CM04RC08T(THIN) | 3 | 1000 (at 200MHz) | 0.2 | 0.5 | | |
| CM04RC05T | 4 | 800 (at 100MHz) | 0.2 | 0.5 | | |

BU05MCタイプ

| BU05MCダイブ | | | | | | |
|---------------------|----------------------|------------------------------------------|----------------------------------------|----------------------------------------|----------------------------------------|-------------------------------------------------|
| 形名 Ordering code | ライン数 No. of Lines | インピーダンス Impedance [Ω] (typical) | 直流抵抗 DC resistance [Ω] (max.) | 定格電流 Rated current [A] (max.) | 定格電圧 Rated voltage [V] (D.C.) | 絶縁抵抗 Insulation resistance [MΩ] (min.) |
| BU05MC01T | | 1000 (at 60MHz) | 0.12 | 1 | | |
| BU05MC03T | | 600 (at 100MHz) | 0.10 | 1.5 | | |
| BU05MC05T | 2 | 1700 (at 130MHz) | 0.12 | 1 | | |
| BU05MC07T | | 1200 (at 250MHz) | 0.11 | 1 | 50 | 100 |
| BU05MC13T | | 1000 (at 200MHz) | 0.06 | 1 | 30 | 100 |
| BU05MC02T | | 1000 (at 150MHz) | 0.15 | 0.5 | | |
| BU05MC08T | 3 | 700 (at 60MHz) | 0.11 | 0.5 | | |
| BU05MC11T | | 800 (at 350MHz) | 0.09 | 0.5 | | |

セレクションガイド Selection Guide



アイテム一覧 Part Numbers

P.367



特性図 Electrical Characteristics





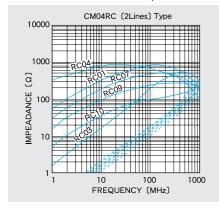


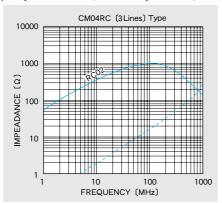


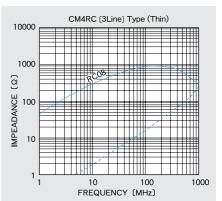


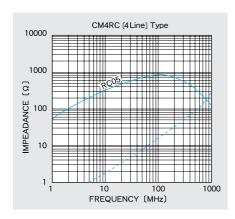


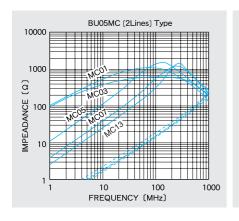
インピーダンス周波数特性例 Impedance -vs- Frequency characteristics(Measured by HP4291A)

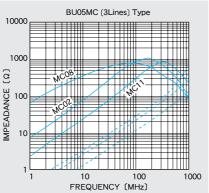










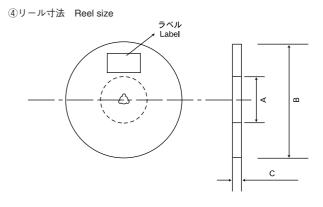


----- コモンモード ----- ノーマルモード

梱包 PACKAGING

①標準数量 Standard quantity

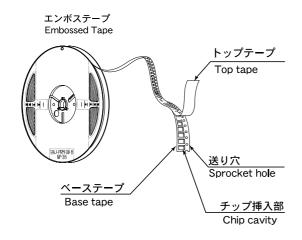
| | 標準数量 (pcs.) | | | | |
|------------------------------|-------------------|--|--|--|--|
| Type | Standard quantity | | | | |
| туре | テーピング | | | | |
| | Taping | | | | |
| CM04RC [2 Lines] type | 1500 | | | | |
| CM04RC [3 Lines] type | 1000 | | | | |
| CM04RC [3 Lines] type (Thin) | 2500 | | | | |
| CM04RC [4 Lines] type | 1000 | | | | |
| BU05MC [2 Lines] type | 2500 | | | | |
| BU05MC [3 Lines] type | 2500 | | | | |
| | | | | | |



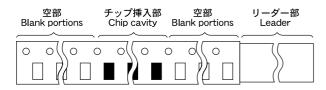
| Туре | АВ | | С |
|--------|------------------------|--------------------------|-------------------|
| CM04RC | φ100±1 | φ330±2 | 18±1.5 |
| | (\$\phi 3.94\pm 0.039) | (<i>ϕ</i> 12.99±0.079) | (0.709 ± 0.059) |
| BU05MC | φ80±1 | φ330±2 | 13.5±1 |
| | (\$\phi 3.15\pm 0.039) | (\$\phi\$12.99\pmu0.079) | (0.53 ± 0.039) |

Unit: mm(inch)

②テーピング材質 Tape Material



③リーダー部・空部 Leader and Blank Portion

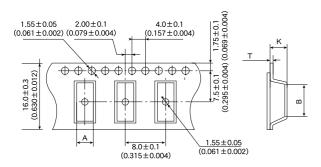


引き出し方向 Direction of tape feed

| | Туре | リーダー部 Leader | 空部 (リーダー部側) Blank portions (Leader side) | 空部 (チップ挿入部側) Blank portions (Chip cavity side) |
|---|--------|-----------------|---------------------------------------------------|---------------------------------------------------------|
| (| CM04RC | 150(5.89) | 80(3.14) | 80(3.14) |
| | BU05MC | 150(5.89) | 80(3.14) | 80(3.14) |

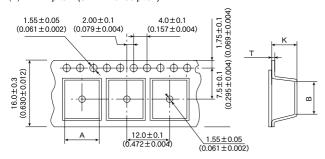
00(0.14)

エンボステープ (CM04RCタイプ) Embossed tape (CM04RC type) (1) 8mm pitch (0.31 inches pitch)

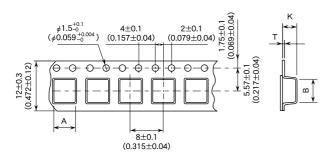


挿入ピッチ チップ挿入部 テープ厚み ライン数 Type Insertion Chip cavity Tape thickness Lines pitch Т В Κ 5.7±0.1 0.4±0.05 8.0 ± 0.1 9.65 ± 0.1 5.2max 3 12.0±0.1 9.8±0.1 7.7 ± 0.1 0.38±0.05 5.0max CM04RC 3 (THIN) 8.0 ± 0.1 5.7 ± 0.1 9.8 ± 0.1 3.1max 0.4 ± 0.05 12.0±0.1 10.3±0.1 10.3±0.1 5.0max 0.3±0.05 BU05MC 2 8.0±0.1 5.35±1.5 5.7±0.2 3.2±0.1 0.4±0.05 BU05MC 3

(2) 12mm pitch (0.472 inches pitch)

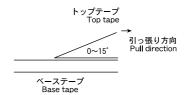


エンボステープ (BU05MCタイプ) Embossed tape (BU05MC type)



⑥トップテープ強度 Top Tape Strength

トップテープのはがし力は、下図矢印方向にて $0.1\sim0.7N$ となります。 The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illutrated below.



1/4

| ltem | Surface Mount High current inductors 08 Type | Surface Mount High current inductors 04/05/06 Type | CommonMode Choke Coils CM04RC | CommonMode Choke Coils BU05MC | Balun Transformers BU05MC | Test | Method | and Remarks | |
|-----------------------------------------------------------|----------------------------------------------------|----------------------------------------------------------|-------------------------------------|-------------------------------------|------------------------------|-------------------------------------|----------------------------------------|---------------------|---------------|
| 1.Operating Temperature | -25°C~+85°C | -25~+105°C | | | | Including self-genera | ted hea | t | |
| Range 2.Storage Temperature | -40°C~+85°C | | | | | Commom mode cho | ro soil B | talum transformers | |
| Range | 400-1000 | | | | | -5 to +40°C in taped | | | • |
| 3.Rated current | Within the specifica | ation | Within the specified | d tolerance | | MSD inductor: | · paonag | ····9 | |
| | | | | | | The maximum DC va | alue hav | ing inductance de | crease |
| | | | | | | within specified value | and ter | mperature increas | se within |
| | | | | | | 40°C by the application | on of DC | bias. | |
| | | | | | | Inductance decrease | | | |
| | | | | | | 04 | 05 | 06 | |
| | | | | | | 30% | 20% | 10% | |
| | | | | | | | | | |
| | | | | | | Commom mode cho | ke coil: | | |
| | | | | | | The maximum DC value | having to | emperature increase | within speci- |
| | | 1 | | | | fied temperature,as de | | | on. |
| 4.Impedance | | | Within the specified | d tolerance | | Commom mode cho | | | |
| | | | | | | Measuring equipmer | | | alent |
| 5. Inductance | Within the specified | t tolerance | | | Refer to individual | Measuring frequency SMD inductor: | · Spec | ified frequency | |
| 5. Inductance | Within the specified | Tolerance | | | specification | Measuring equipmer | nt:HP 4 | 12844 or its equiv | alent |
| | | | | | оростоиноп | Measuring frequency | | | aioni |
| | | | | | | Measuring voltage: 1\ | | | s connection |
| 6.DC Resisitance | Within the specified | d tolerance | | | - | SMD transformer • SM | D inducto | or • Commom mode | choke coil: |
| | | | | Measuring equipmen | nt:DC o | hmmeter | | | |
| 7.Self resonance frequency | Within the specifica | Within the specification | | | | SMD inductor: | | | |
| | | | | | | Measuring equipmer | | | |
| | | | | | | (HP 4191A, 4192A) | or its eq | uivalent | |
| 8.Temperature characteris- tic | 04, 05, 06 Type: V | | | | | SMD inductor : | | de terre te | |
| uc | 08Type: Within±5 | 20 | | | | Change of maximum Temperature at | | 20°C | step i to 5 |
| | | | | | | Temperature at | зюр і | Minimum opera | ating |
| | | | | | | Temperature at | step 2 | temperature | 9 |
| | | | | | | Temperature at | step 3 | 20°C (Standard te | emperature) |
| | | | | | | Temperature at | ctop 4 | Maximum opara | ating |
| | | | | | | remperature at | siep 4 | temperature | |
| | | | | | | Temperature st | step 5 | 20℃ | |
| O Parisitana e to file | | ı | | | <u> </u> | 0 | | | |
| Resisitance to flexure of substrare | | | Can satisfy the con | ditions of the chart | at right. | Commom mode cho Accoding to JIS C00 | | | |
| Substrate | | | | | | Account to 315 Coo | _ | 04RC · BU05MC | 1 |
| | | | | | | Warp | Olvio | 3mm | |
| | | | | | | Pressing speed | | 0.5mm/sec. | |
| | | | | | | Duration | | 5±1sec. | |
| | | | | | | | | | _ |
| | | | | | | | ressig | Jig | |
| | | | | | | | R340 | | |
| | | | | | | | \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\ | t=1mm) | |
| | | | | | | | | Board | |
| | | | | | | R5 45+3r | T., | i+2mm | |
| | | | | | | 45±2r | ************************************** | 5±2mm | |
| | | | | | | | | | |
| | | | | | | - | | | |

| | | | Specifled Value | | | | | |
|-------------------------------------------------|---------------------------------------------------------------------------|----------------------------------------------------------|--------------------------------------------------------------|-------------------------------------|-----------------------------------------------------------------|------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------|
| | | | | | | | | |
| ltem | Surface Mount High current inductors 08 Type | Surface Mount High current inductors 04/05/06 Type | CommonMode Choke Coils CM04RC | CommonMode Choke Coils BU05MC | Balun Transformers BU05MC | | Test Metho | d and Remarks |
| 10.Standard donndityonn | When there are que In order to provide of ture, 45 to 85% rela | tive humidity and 86 | f 20±2°C of tempera- | | | | | |
| 11.Insulation resistance : between wires | 100MΩ min. | | | | | SMD inductor : Applied voltage | : 100VDC | Duration: 60sec. |
| | | | | | 1 | Commom mode Applied voltage Duration: 60 se | : Rated vol | |
| 12.Insulation resistance: between wire and core | 100MΩ min. | | | | | SMD inductor: Applied voltage | : 100VDC | Duration: 60sec. |
| 13.Rated current | | | Within the specifica | ation | | | | |
| 14.Withstanding voltage : between wires | | | No abnormality | | | Commom mode Applied voltage Duration: 60 se | Regulatio | |
| 15.Withstanding voltage: between wire and core | No abnormality | | | | | SMD inductor: Applied voltage Duration: 60 se | | |
| 16.Adhesion of terminal electrode | No abnormality | | | | | | and apply sp | to top surface of specimen mounted pecified static load for 5 sec. |
| 17.Resisitance to vibration | Impedance change | : Within: ±5% | Refer to individual specification. | | Frequency rai Amplitude: 1.5 Mounting met Recovery: At | C0040 ars each in X, ange: 10 to form (Shall n thod: solde t least 2 hrs andition afte arement with | , Y, and Z directions. Total : 6 hrs 55 to 10 Hz (1 min.) of exceed acceleration 196m/s²) ring onto printed board of recovery under the standard r the test,followed by the mea- | |
| 18.Solderability | 95% or more of mounting terminal side shall be covered with tresh solder. | | At least 75% of terminal electrode is covered by new solder. | | SMD inductor Solder tempe Duration: 2± Immersion de | epth: All side be im | des of mounting terminal shall mersed. | |
| | | | | | | Durati | on | 2±0.5 sec. Up to 0.5mm from terminal root |

| | | | Specifled Value | | | | | |
|----------------------------------|----------------------------------------------------|----------------------------------------------------------|-------------------------------------|-------------------------------------|------------------------------|--------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Item | Surface Mount High current inductors 08 Type | Surface Mount High current inductors 04/05/06 Type | CommonMode Choke Coils CM04RC | CommonMode Choke Coils BU05MC | Balun Transformers BU05MC | | Test Method and F | Remarks |
| 19.Resisitance to soldering heat | No abnormality | Official type | Refer to individual: | | | Fenperature parge Duration Recovery Commom ① Reflow Preheat Peak: | Recommended reflow Recomm | 10 150 150 200 ion(sec.) rery under the standard oval from test chamber, urement within 24 hrs. |
| | | | | | | Number 2 Manual Solder t Duration Recove | r of reflow: Within 2 timesoldering emperature: 350±5°C n: 3±1sec. ry: 1 to 2 hrs of recover condition after the temperature. | ery under the standard |
| 20.Thermal shock | Inductance change: V | Vithin:±10% | Refer to individual | specification. | | SMD induce Step 1 2 3 4 SMD induce Step 1 2 3 4 Number of Recovery Commom Accoding t Conditions 1 2 3 4 Number of | o JIS C0025 ctor(08 type) Conditions of 1 c Temperature(°C) -25+3 Room temperature +85+2 Room temperature ctor(04, 05, 06 type) Conditions of 1 c Temperature(°C) -25+3 Room temperature +105+2 Room temperature cycyle: 10 cycles At least 2 hrs of reco condition after the rem followed by the measu mode choke coil: o JIS C0025 of 1 cycle Temperature(°C) CM04RC · BU05MC -25±3°C Room temperature 85±2°C Room temperature cycyle: 10 cycles | Duration(min) 30±3 Within 3 30±3 Within 3 Vicle Duration(min) 30±3 Within 3 Within 3 Viry under the standard oval from test chamber, urement within 24 hrs. Duration(min) 30±3 3 30±3 3 def the standard condi- |

| | | | Specifled Value | | | | |
|-------------------------------|----------------------------------------------------|----------------------------------------------------------|-------------------------------------------------------------------------------|----------------|---|-------------------------|------------------------------------------------------------------------|
| Item | Surface Mount High current inductors 08 Type | Surface Mount High current inductors 04/05/06 Type | CommonMode CommonMode Choke Coils CM04RC BU05MC CM05MC Test Method and Remark | | | | |
| 21.Damp heat (steady state) | | | Refer to individual | specification. | - | Commom mode chol- | ke coil: |
| , | | | | ., | | | CM04RC · BU05MC |
| | | | | | | Temperature | 40±2℃ |
| | | | | | | Humidity | 90~95% |
| | | | | | | Duration | 1000±24 |
| | | | | | | | |
| 22.Loading under damp heat | Inductance change: | Within: ±10% | Refer to individual | specification. | | SMD inductor: | |
| | | | | | | Temperature: 40±2 | °C |
| | | | | | | Humidity: 90~95% | |
| | | | | | | Applied current: Rat | |
| | | | | | | Duration: 240±2hrs | |
| | | | | | | 1 | 2 hrs of recvery under the standard |
| | | | | | | | after rhe removal from test chamber, |
| | | | | | | | by the measurement within 24 hrs. |
| | | | | | | Commom mode chok | CM04RC · BU05MC |
| | | | | | | Tomporaturo | 40±2°C |
| | | | | | | Temperature Humidity | 90~95% |
| | | | | | | Applied current | Rated current |
| | | | | | | Duration | 1000±24 |
| | | | | | | | of recovery under the standard condi- |
| | | | | | | 1 | the removed from test chamber |
| 23.High temperature life test | Inductance change: V | Vithin: ±10% | Refer to individual | specification. | | SMD inductor : | |
| | | | | | | Temperature: | |
| | | | | | | SMD inductor: 10 | 5±3℃ |
| | | | | | | Duration: | |
| | | | | | | SMD inductor: 24 | 0±2hrs |
| | | | | | | Recovery: At least | 2 hrs of recvery under the standard |
| | | | | | | | after rhe removal from test chamber, by the measurement within 24 hrs. |
| | | | | | | Commom mode chok | ke coil: |
| | | | | | | | CM04RC · BU05MC |
| | | | | | | Temperature | 85±2℃ |
| | | | | | | Duration | 1000±24 |
| | | | | | | Recovery: 1~2 hrs | of recovery under the standard condi- |
| | | | | | | tion after | the removed from test chamber |
| 24 Low Tomporature life Te-+ | Inductance change: V | Vithin * +100∕ | Refer to individual | enecification | | SMD inductor : | |
| 24.Low Temperature life Test | muuciance change . V | viuiiII • ± 1∪70 | Refer to individual | apecincanon. | | Temperature: -40± | -3°C |
| | | | | | | Duration: | - |
| | | | | | | SMD inductor: 240 | 0±2hrs |
| | | | | | | | 2 hrs of recvery under the standard |
| | | | | | | condition | after rhe removal from test chamber, by the measurement within 24 hrs. |
| | | | | | | | |
| | | | | | | Commom mode chol | |
| | | | | | | T | CM04RC · BU05MC |
| | | | | | | Temperature | -40±3℃ |
| | | | | | | Duration Duration | 1000±24 |
| | | | | | | | of recovery under the standard condi- |
| | | | | | | tion after | the removed from test chamber |

PRECAUTIONS

delivery.

| SMD Inductors, CM04RC. | BU05MC | |
|------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Stages | Precautions | Technical considerations |
| 1.Circuit Design | Operating environment, 1.The products described in this specification are intended for use in general electronic equipment, (office supply equipment, telecommunications systems, measuring equipment, and household equipment). They are not intended for use in mission-critical equipment or systems requiring special quality and high reliability (traffic systems, safety equipment, aerospace systems, nuclear control systems and medical equipment including life-support systems,) where product failure might result in loss of life, injury or damage. For such uses, contact TAIYO YUDEN Sales Department in advance. | |
| 2.PCB Design | Land pattern design 1.Please contact any of our offices for a land pattern, and refer to a recommended land pattern of specifications. | |
| 3.Considerations for automatic placement | Adjustment of mounting machine 1.Excessive impact load should not be imposed on the products when mounting onto the PC boards. 2.Mounting and soldering conditions should be checked beforehand. | When installing products, care should be taken not to apply distortion stress as it may deform the products. |
| 4.Soldering | Reflow soldering 1.Please contact any of our offices for a reflow soldering, and refer to the recommended condition specified. 2.This products is reflow soldering only. 3.SMD Inductors Please do not add any stress to a product until it returns in normal temperature after reflow soldering. Lead free soldering 1.When using products with lead free soldering, we request to use them after confirming of adhesion, temperature of resistance to soldering heat, soldering etc sufficiently. Recommended conditions for using a soldering iron: Put the soldering iron on the land-pattern. Soldering iron's temperature - Below 350 °C Duration - 3 seconds or less The soldering iron should not directly touch the inductor. | 1.If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products. |
| 5.Cleaning | Cleaning conditions 1.SMD Inductors Please contact any of our offices for a cleaning, | |
| 6.Handling | Handling 1.Keep the product away from all magnets and magnetic objects. Breakaway PC boards (splitting along perforations) 1.When splitting the PC board after mounting product, care should be taken not to give any stresses of deflection or | 1. There is a case that a characteristic varies with magnetic influence. 1. Planning pattern configurations and the position of products should be carefully performed to minimize stress. |
| | twisting to the board. 2.Board separation should not be done manually, but by using the appropriate devices. Mechanical considerations 1.Please do not give the product any excessive mechanical shocks. 2.SMD Inductors Please do not add any shock and power to a product in transportation. | 1. There is a case to be damaged by a mechanical shock. 2. SMD Inductors There is a case to be broken by the handling in transportation. |
| | Pick-up pressure 1.SMD Inductors Please do not push to add any pressure to a winding part. Please do not give any shock and push into a ferrite core exposure part. Packing 1.SMD Inductors Please avoid accumulation of a packing box as much as | 1.SMD Inductors Damage and a characteristic can vary with an excessive shock or stress. 1.There is a case that transformation and a product of tape are damaged by |
| 7.Storage conditions | possible. Storage 1.To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled • Recommended conditions Ambient temperature 0~40°C Humidity Below 70% RH The ambient temperature must be kept below 30°C. Even under ideal storage conditions, solderability of products electrodes may decrease as time passes. For this reason, product should be used within one year from the time of | accumulation of a packing box. 1. Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place. |